

C. Huang et al.  
U.S. Serial No. 09/823,176  
Page 2 of 7

B1  
1. (Amended) A substrate strip, which comprises:

(a) a frame having a pair of parallel supporting bars including a first supporting bar and a second supporting bar; and

(b) at least one substrate supported on the supporting bars, the substrate being temporarily linked to the supporting bars by means of no more than two tie bars, so as to allow thermally-induced expansion of the substrate to be directed toward corners of the substrate free of the tie bars, and allow the substrate to be free of connection to the tie bars in a semiconductor package formed on the substrate.

B2  
9. (Amended) A substrate strip, which comprises:

(a) a frame having a pair of parallel supporting bars including a first supporting bar and a second supporting bar; and

(b) at least one substrate supported on the supporting bars, the substrate being temporarily linked to the supporting bars by means of a two-point linkage structure consisting of just two tie bars linked to the supporting bars, so as to allow thermally-induced expansion of the substrate to be directed toward corners of the substrate free of the tie bars, and allow the substrate to be free of connection to the tie bars in a semiconductor package formed on the substrate.

B3  
14. (Amended) A substrate strip, which comprises:

(a) a frame having a pair of parallel supporting bars including a first supporting bar and a second supporting bar; and

(b) at least one substrate supported on the supporting bars, the substrate being temporarily linked to the supporting bars by means of a one-point linkage structure consisting of just one tie bar linked to one of the two supporting bars, so as to allow thermally-induced expansion of the substrate to be directed toward corners of the substrate free of the tie bar, and allow the substrate to be free of connection to the tie bar in a semiconductor package formed on the substrate.